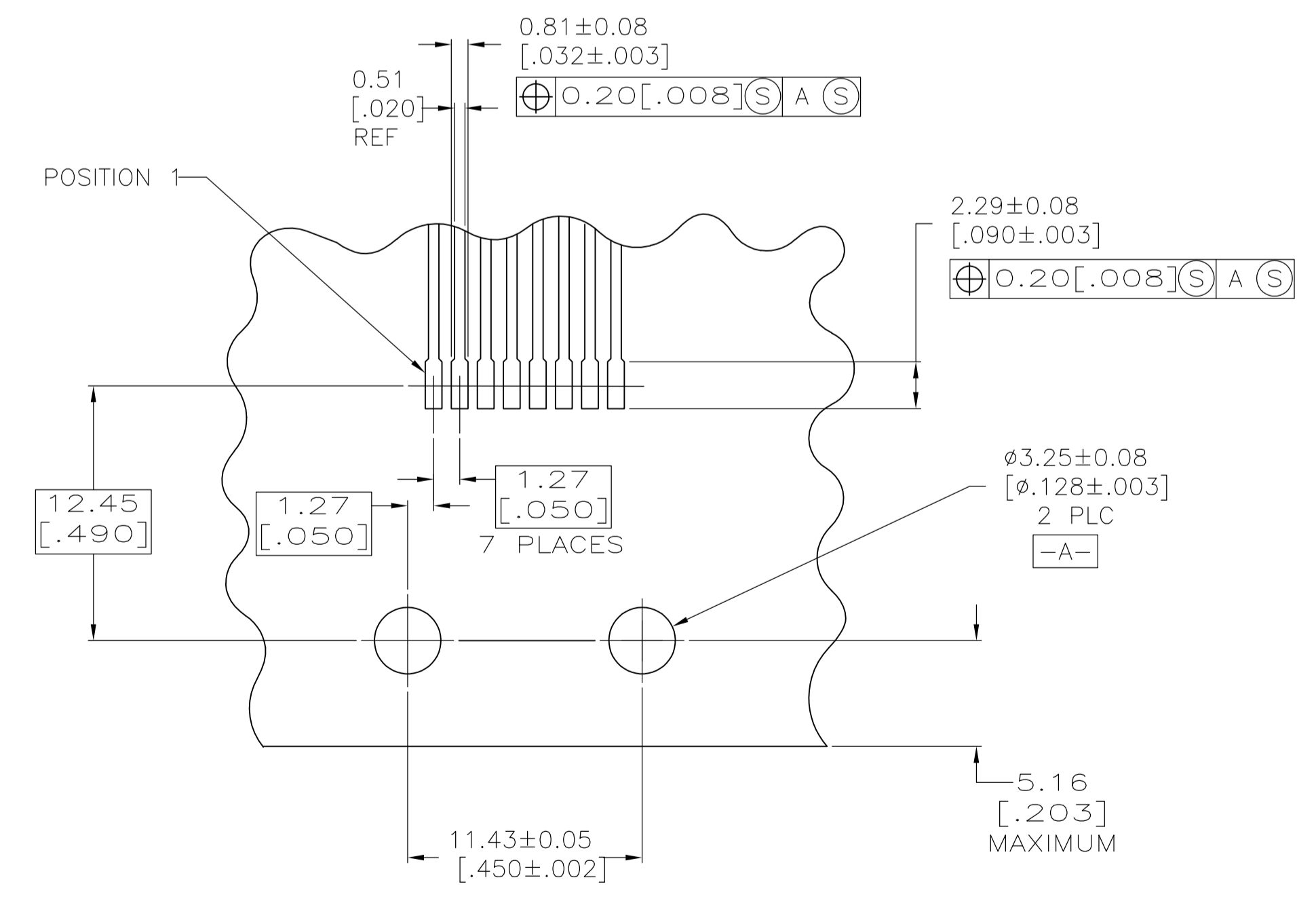
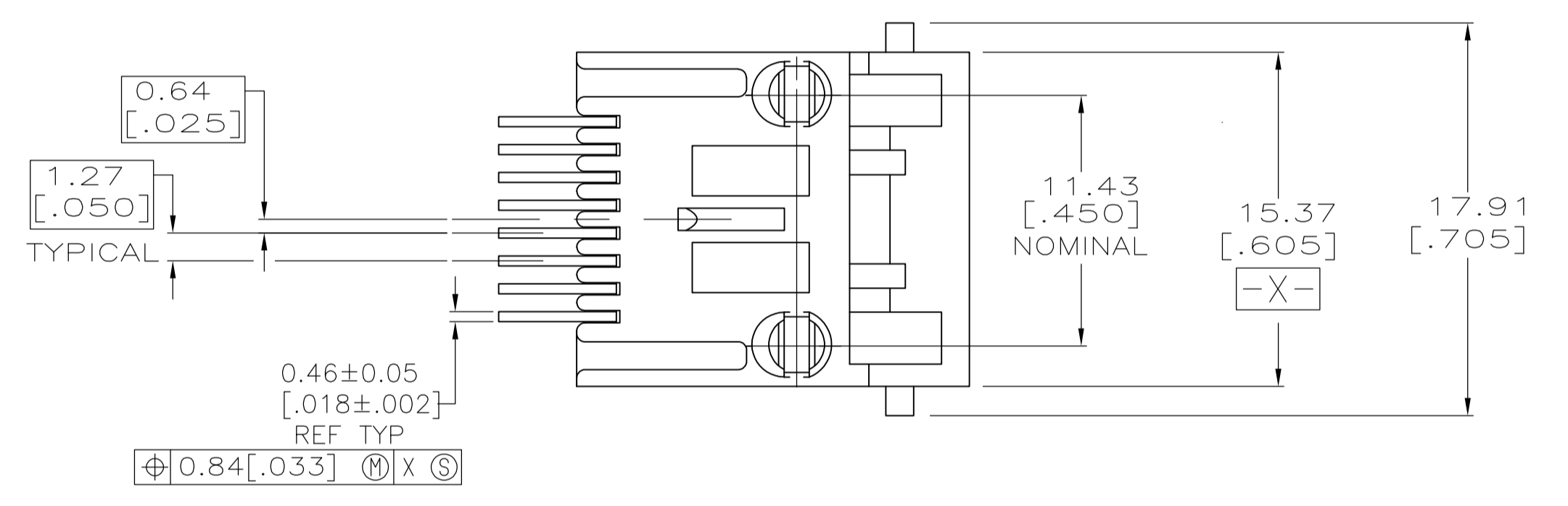
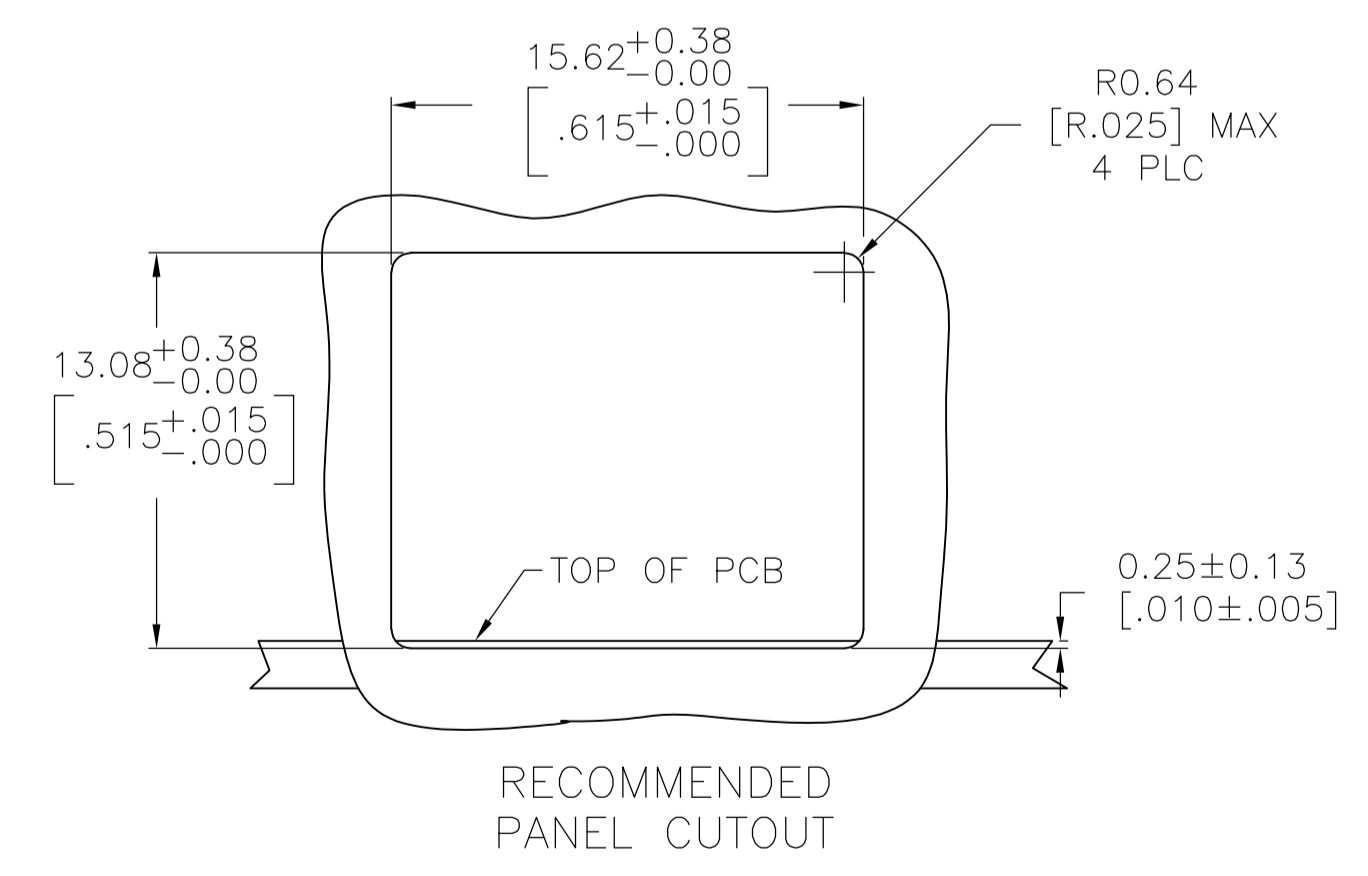


- MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK
 TERMINAL - 0.36 [0.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [0.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [0.062±0.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PRINTED CIRCUIT BOARD COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 08/JUN/2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN	APVD S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME: MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, WITH PANEL STOPS		
0 PLC ± -	1 PLC ± -	PRODUCT SPEC: 108-1163		
2 PLC ± -	3 PLC ± -	APPLICATION SPEC: 114-6040		
4 PLC ± -	ANGLES ± -	SIZE: A1	CAGE CODE: 00779	DRAWING NO: 5555248
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	CUSTOMER DRAWING	SCALE: 4:1 SHEET 1 OF 1 REV B